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PATENT TRADEMARK OFFICE

Patent
Case No.: 53434US009

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

First Named Inventor: HOGERTON, PETER B.

Application No.: 09/690,600

Group Art Unit: 2827

Filed: October 17, 2000

Examiner: Luan C. Thai

Title: SOLVENT ASSISTED BURNISHING OF PRE-UNDERFILLED SOLDER-BUMPED WAFERS FOR FLIPCHIP BONDING

REQUEST FOR EXTENSION OF TIME UNDER 37 CFR § 1.136(A)Commissioner for Patents
Washington, DC 20231

CERTIFICATE OF TRANSMISSION

To Fax No.: 703-872-9318

I hereby certify that this correspondence is being facsimile transmitted to the U.S. Patent and Trademark Office on:

27 Jan 2003
DateDean M. Harts
Dean M. Harts

Dear Sir:

This is a request for an extension of time under the provisions of 37 CFR § 1.136(a).

Please charge the following fee to Deposit Account No. 13-3723:

- ☒ 37 CFR § 1.17(a)(1) - Extension within first month
☐ 37 CFR § 1.17(a)(2) - Extension within second month
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Please also charge any additional fees, or credit any overpayment to Deposit Account

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Respectfully submitted,

27 Jan 2003
Date

By:

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